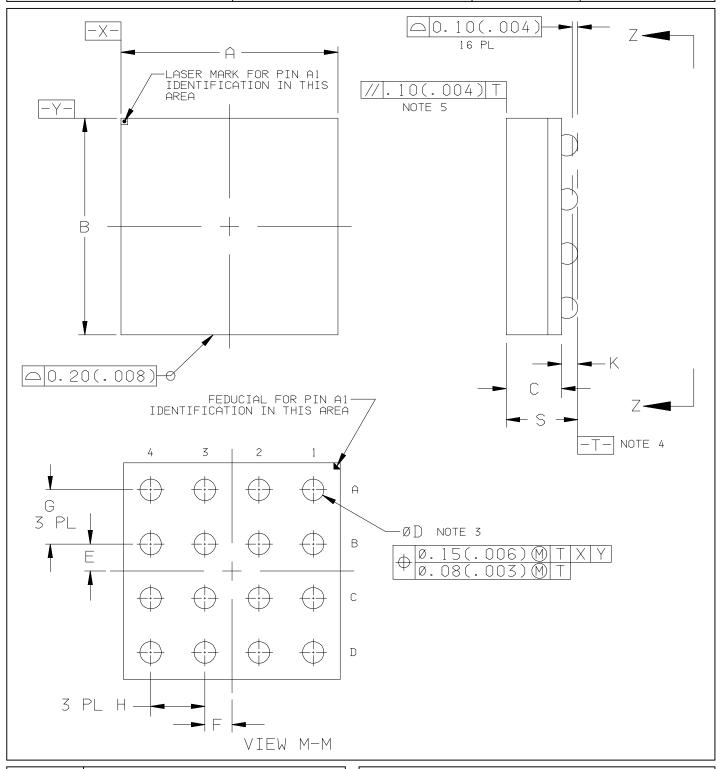
ON Semiconductor	MECHANICAL OUTLINES DICTIONARY	98A0N04307D	
ON SUMEORIQUE LOS		PAGE 489	
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CASE NO.	489-01
STATUS	ON SEMICONDUCTOR STANDARD
NEW STD	
USED ON	16 PIN FLIP CHIP BGA 4 X 4, 1.0MM PITCH

ON Semiconductor	MECHANICAL OUTLINES DICTIONARY	98AON04307D	
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## NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.
- 3. DIMENSION D IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL DATUM PLANE -T-.
- 4. DATUM -T- (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

	MILLIMETERS	INCHES		MILLIMETERS	INCHES
DIM	MIN MAX	MIN MAX	DIM	MIN MAX	MIN MAX
A	4.00 BSC	0.157 BSC			
В	4.00 BSC	0.157 BSC			
С	1.02 REF	0.040 REF			
D	Ø0.30 Ø0.50	Ø0.012 Ø0.020			
E	0.50 BSC	0.020 BSC			
F	0.50 BSC	0.020 BSC			
G	1.00 BSC	0.039 BSC			
Н	1.00 BSC	0.039 BSC			
K	0.25 0.35	0.010 0.014			
S	1.40 MAX	0.055 MAX			
CASE NO.	489-01				
STATUS	ON SEMICONDU	ICTOR STANDARD			
NEW STD					
USED ON	16 PIN FLIP 4 X 4, 1.0M				

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